

## Amendments to Claims

This listing of claims will replace all prior versions and listings of claims in the application:

### Listing of Claims

1. (currently amended) A method for forming an apparatus configured to reduce electromagnetic interference between a pair of antennas coupled to a wireless communication device, wherein the method comprises:

extracting a shape of the apparatus from a thin sheet of conductive material;

folding the shape into a plurality of resonant circuit elements, each configured to resonate at a known carrier frequency of a signal transmitted by one of the pair of antennas;  
and

providing a wavelength of a carrier frequency of a signal transmitted by one of the pair of antennas;

resonating each of the resonant circuit elements at a carrier frequency of the signal transmitted by one of the pair of antennas; and

wherein by the steps of extracting and folding, the apparatus is formed having such that a combined length of the plurality of resonant circuit elements extending in a plane parallel to a plane that is coplanar with the planar portions of the pair of antennas, and extends a spaced distance from one antenna towards the other antenna, and said extension is substantially equal to one-half of a wavelength corresponding to the known carrier frequency.

2. (previously presented) The method of claim 1, wherein a process of extracting the shape from the thin sheet of conductive material is selected from a group comprising stamping, laser etching, and chemical etching.
3. (original) The method of claim 2, wherein the conductive material comprises a relative permittivity value of about 0.0 F/m to about 1.0 F/m and a relative permeability value of about 10 H/m to about 100,000 H/m.
4. (original) The method of claim 2, wherein the conductive material comprises a metal selected from a group comprising iron (Fe), copper (Cu), gold (Au), silver (Ag), tin (Sn), and nickel (Ni), or a metal alloy selected from a group comprising beryllium copper (BeCu), phosphor bronze (Ph+Cu/Zn/Sn), magnesium alloys (Mg/Al/O) and steel (Fe/C).
5. (original) The method of claim 2, wherein the conductive material comprises a primarily ferrous-based material.
6. (original) The method of claim 1, wherein the plurality of resonant circuit elements comprise a plurality of rectangular elements connected to and arranged above a common reference plane by a plurality of vertical segments, wherein the plurality of rectangular elements and the common reference plane comprise capacitive portions, and the plurality of vertical segments comprise inductive portions, of the plurality of resonant circuit elements.
7. (original) The method of claim 6, wherein the method further comprises arranging a dielectric material between the plurality of rectangular elements and the common reference plane.
8. (original) The method of claim 1, wherein the plurality of resonant circuit elements comprise a plurality of A-shaped elements separated by a plurality of horizontal segments, wherein flat surfaces of the A-shaped elements comprise capacitive portions, and bent portions

of the A-shaped elements comprise inductive portions, of the plurality of resonant circuit elements.

9. (original) The method of claim 1, wherein the plurality of resonant circuit elements comprise a plurality of relatively long domed elements spaced apart by a plurality of relatively thin slots, and wherein the slots comprise capacitive portions, and the domed elements comprise inductive portions, of the plurality of resonant circuit elements.

10.- 23. (canceled)

24. (previously presented) The method of claim 9, wherein the method further comprises arranging a dielectric material within the relatively thin slots between the plurality of relatively long domed elements.

25. (previously presented) The method of claim 1, wherein a thickness of the thin sheet of conductive material is selected from a range of thicknesses comprising about 0.1 mm to about 0.2 mm.

26. (previously presented) The method of claim 1, wherein by the steps of extracting and folding, the plurality of resonant circuit elements are formed having a periodic surface that is less than or equal to one-tenth of the wavelength corresponding to the carrier frequency.

27. (previously presented) The method of claim 1, wherein by the steps of extracting and folding, the apparatus is formed without a dielectric substrate.